

Product Specification – Mar. 24, 2004 V.6 Supersedes Date of Sep. 30, 2003



DATA SHEET

NETWORK CHIP RESISTORS

YC158 (10Pin/8R) 5%





Chip Resistor Surface Mount YC SERIES 158

SCOPE

This specification describes YCI58 series chip resistors made by thick film process.

ORDERING INFORMATION

Part number is identified by the series, size, tolerance, packing style, temperature coefficient, special type and resistance value.



SCHEMATIC



W₂ (mm)

CCB261_a

Fig. 2 YCI58 series chip resistors construction



1.6±0.15

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POWER RATING

RATED POWER AT 70°C, YC158=1/32W FOR ELEMENT



RATED VOLTAGE:

The DC or AC (rms) continuous working voltage corresponding to the rated power is determined by the following formula:

 $V=\sqrt{(P X R)}$

Where

V=Continuous rated DC or AC (rms) working voltage (V)

P=Rated power (W)

R=Resistance value (Ω)

ELECTRICAL CHARACTERISTICS

Table 2			
CHARACTERISTICS	YC158 1/32W		
Operating Temperature Range	–55°C to +125°C		
Maximum Working Voltage	25V		
Maximum Overload Voltage	50V		
Dielectric Withstanding Voltage	50V		
Number of Resistors	8		
Resistance Range	10Ω to 100KΩ Zero Ohm Jumper <0.05Ω		
Temperature Coefficient	±200ppm/°C		
Jumper Criteria	Rated Current 1.0A		
Jumper Criteria	Maximum Current 2.0A		



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<u>TAPING REEL</u>

Table 3	
DIMENSION	YC158
Tape Width	8mm
ØA (mm)	180+0/-3
ØB (mm)	60+1/_0
ØC (mm)	13.0±0.2
ØD (mm)	21±0.8
W (mm)	9.0±0.3
T (mm)	.4±



PAPER TAPE SPECIFICATION

Table 4	
DIMENSION	YC158
A (mm)	2.0±0.1
B (mm)	3.5±0.1
W (mm)	8.0±0.2
E (mm)	1.75±0.1
F (mm)	3.5±0.05
P ₀ (mm)	4.0±0.1
P1 (mm)	4.0±0.1
P ₂ (mm)	2.0±0.05
ØD₀ (mm)	1.5+0.1/-0
T (mm)	0.85±0.10



PACKING METHOD

LEADER/TRAILER TAPE SPECIFICATION



PACKING STYLE	REEL DIMENSION	YC158
Paper Taping Reel (R)	7" (178 mm)	5,000
	13" (330 mm)	20,000

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ТҮРЕ	TEST METHOD				ACCEPTANCE STANDARD
Temperature Coefficient of (T.C.R.)Measure resistance at +25°C or specified room temperature as R1, then measure at -55°C or +125°C respectively as R2.FormulaT.C.R. = $\frac{R_2-R_1}{R_1(t_2-t_1)} \times 10^6 \text{ (ppm/°C)}$ Where $t_1=+25°C \text{ or specified room temperature}$ temperature coefficient of resistance from the following formula:T.C.R. = $\frac{R_2-R_1}{R_1(t_2-t_1)} \times 10^6 \text{ (ppm/°C)}$		in ohms	Refer to table 2		
Thermal Shock	At $-55\pm3^{\circ}$ C for 2 minutes and at $+125\pm2^{\circ}$ C for 2 minutes as one cycle. After 5 cycles, the specimen shall be stabilized at room temp. Measure the resistance to determine Δ R/R(%) after one more hour.			±(1.0%+0.05Ω)	
Low Temperature Operation	Place the specimen in a test chamber maintained at $-65 (+0/-5)^{\circ}$ C. After one hour stabilization at this temperature, full rated working voltage shall be applied for 45 (+5/-0) minutes. Have 15 (+5/-0) minutes after remove the voltage, the specimen shall be removed from the chamber and stabilized at room temperature for 24 hrs. Measure the resistance to determine $\Delta R/R(\%)$.			±(1.0%+0.05Ω) No visible damage	
Short Time Overload	for 5 seconds. Have the specimen stabilized at room temperature for 30 minutes		±(2.0%+0.05Ω) No visible damage		
Insulation Resistance	Place the specimen in the jig a continues overload voltage (R minute as shown. Measure the insulation resistar	.C.O.V) for one	Type Voltage (DC)	YC158 50V	≥10,000MΩ
Dielectric Withstand Voltage	Place the specimen in the jig a specified value continuous over shown for one minute.		Type Voltage (AC)	YC158 50Vrms	Breakdown voltage> specification and without open/short
Resistance To Soldering Heat	g specimen stabilized at room temperature for 30 minutes minimum.		±(1.0%+0.05Ω) No visible damage		

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TYPE	TEST METHOD		ACCEPTANCE STANDARD
Moisture Resistance	Place the specimen in the test chamber and subject to 42 damp heat cycles. Each one of which consists of the steps 1 to 7 as figure 9. The total length of test is 1,000 hours. Have the specimen stabilized at room temperature for 24 hours after testing. Measure the resistance to determine $\Delta R/R(\%)$.		±(2.0%+0.05Ω) No visible damage
Life	Place the specimen in the oven at 70 \pm 2°C. Apply the rated voltage to the specimen at the 1.5 hours on and 0.5 hour off cycle. The total length of test is 1,000 hours. Have the specimen stabilized at room temperature for one hour minimum after testing. Measure the $\Delta R/R(\%)$.		±(3.0%+0.05Ω) No visible damage
Solderability	Immerse the specimen in the solder pot at 235 ± 5 °C for 5 sec.		At least 95% solder coverage on the termination
Bending Strength	Mount the specimen on a test board as shown in the figure 8. Slowly apply the force till the board is bent for 5 ± 1 sec. Measure the $\Delta R/R(\%)$ at this position.	Type YC158 Bent Distance (d) Imm Position before bend Imm Position before bend Imm Fig. 8 Principle of the bending test	±(1.0%+0.05Ω) No visible damage

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